

CD4062A Types

CMOS 200-Stage Dynamic Shift Register

MAXIMUM RATINGS, Absolute-Maximum Values:

STORAGE TEMPERATURE RANGE (T_{stg})	-65 to +150°C
OPERATING-TEMPERATURE RANGE (T_A):	
PACKAGE TYPES K, T, H	-55 to +125°C
DC SUPPLY-VOLTAGE RANGE, (V_{DD})	
(Voltages referenced to V_{SS} Terminal)	-0.5 to +15 V
POWER DISSIPATION PER PACKAGE (PD):	
For $T_A = -55$ to +100°C (PACKAGE TYPES K, T)	500 mW
For $T_A = +100$ to +125°C (PACKAGE TYPES K, T)	Derate Linearly at 12 mW/°C to 200 mW
DEVICE DISSIPATION PER OUTPUT TRANSISTOR	
For $T_A =$ FULL PACKAGE-TEMPERATURE RANGE (All Package Types)	100 mW
INPUT VOLTAGE RANGE, ALL INPUTS	-0.5 to $V_{DD} + 0.5$ V
LEAD TEMPERATURE (DURING SOLDERING):	
At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79 mm) from case for 10 s max.	+265°C

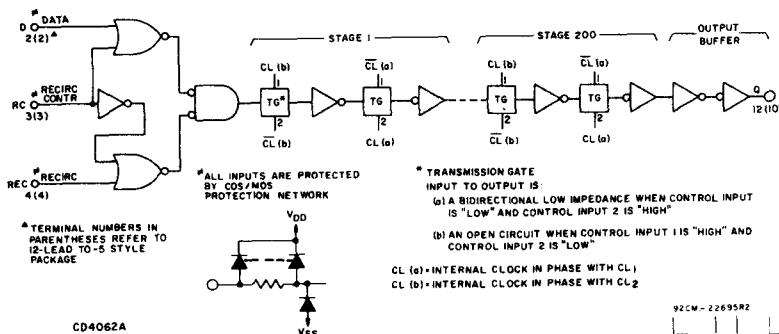
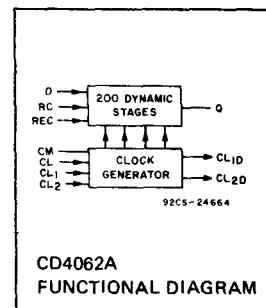


Fig. 1 – CD4062A logic block diagram.

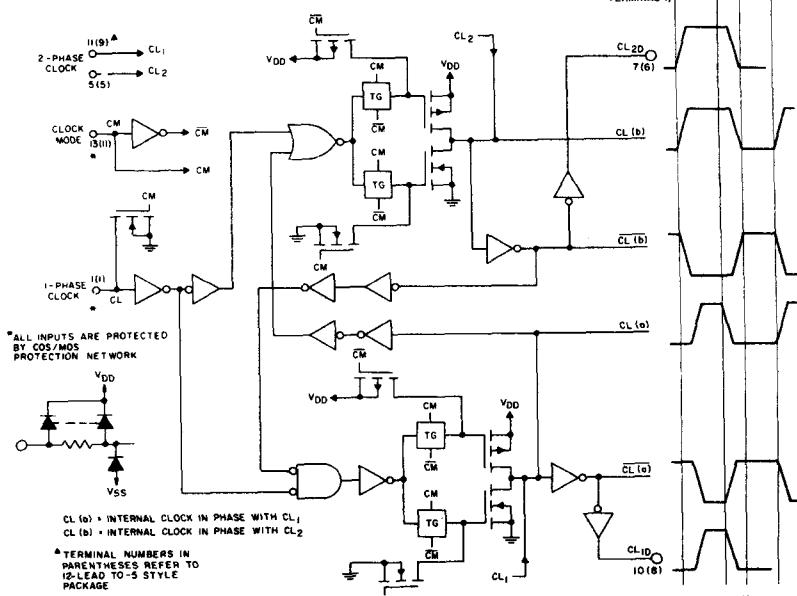


Fig. 2 – Clock circuit logic diagram.

The RCA-CD4062A is a 200-stage dynamic shift register with provision for either single- or two-phase clock input signals. Single-phase-clocked operation is intended for low-power, low clock-line capacitance requirements. Single-phase clocking is specified for medium-speed operation (< 1 MHz) at supply voltages up to 10 volts. Clock input capacitance is extremely low (< 5 pF), and clock rise and fall times are non-critical. The clock-mode signal (CM) must be low for single-phase operation.

Two-phase clock-input signals may be used for high-speed operation (up to 5 MHz) or to further reduce clock rise and fall time requirements at low speeds. Two-phase operation is specified for supply voltages up to 15 volts. Clock input capacitance is only 50 pF/phase. The clock-mode signal (CM) must be high for two-phase operation. The single-phase-clock input has an internal pull-down device which is activated when CM is high and may be left unconnected in two-phase operation.

The logic level present at the data input is transferred into the first stage and shifted one stage at each positive-going clock transition for single-phase operation, and at the positive-going transition of CL₁ for two-phase operation.

The CD4062A-Series types are supplied in 12-lead hermetic TO-5 packages (T suffix), 16-lead ceramic flat packages (K suffix), and in chip form (H suffix).

Features:

- Minimum shift rates over full temperature range—

Single-phase clock: $3 V \leq V_{DD} \leq 10 V$; $f_{min} = 10$ kHz; $-55^\circ C \leq T_A \leq +125^\circ C$ ($f_{min} = 1$ kHz up to $T_A \leq 75^\circ C$)

Two-phase clock: $3 V \leq V_{DD} \leq 15 V$; $f_{min} = 10$ kHz; $-55^\circ C \leq T_A \leq +125^\circ C$ ($f_{min} = 1$ kHz up to $T_A \leq 75^\circ C$)

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RECOMMENDED OPERATING CONDITIONS at $T_A = 25^\circ C$, Except as Noted.
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

CHARACTERISTIC	V_{DD} (V)	LIMITS		UNITS
		MIN.	MAX.	
Supply-Voltage Range (For $T_A = \text{Full Package-Temperature Range}$): Single-Phase Clock		3	10	V
Two-Phase Clock		3	12	
Clock Input Frequency, f_{CL}^*	5 10	0.15 0.15	500 1000	kHz
Clock Pulse Width, t_W^*	5 10	250 500	66.7×10^{-6} 66.7×10^{-6}	ns
Clock Rise or Fall Times, t_{rCL} or t_fCL^*	5 10	— —	10 1	μs
Data Hold Time, t_H^*	5 10	150 50	— —	ns

* For single-phase clock, 50% duty cycle

Two-Phase Clock Operation (CL_1, CL_2); Clock Mode (CM) = High; $3 V \leq V_{DD} \leq 15 V$. See Figure 4.

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS	
		V_{DD} V	MIN.	TYP.	MAX.	
Maximum Clock Input Frequency, f_{CL}		5	1.25	2.5	—	MHz
Minimum Clock Input Frequency, f_{CL}		10	2.5	5	—	
Clock Overlap Time		5	150	10	—	Hz
CL ₂		10	150	10	—	
CL ₁						
td_1						
td_2						
Average Input Capacitance, C_I CL_1, CL_2			—	50	—	pF
Propagation Delays; t_{PHL}, t_{PLH} CL_1 to Q		5	—	250	500	ns
CL_1 to CL_1D CL_2 to CL_2D		10	—	100	200	
Minimum Data Setup Time $t_{S CL_2}$		5	—	250	500	ns
CL_1		10	—	100	200	
$t_{S CL_2}$						
Minimum Data Hold Time $t_{H CL_2}$		5	—	—	0	ns
CL_1		10	—	—	0	
Clock Rise and Fall Times t_{rCL_1, CL_2} t_{fCL_1, CL_2}			No Restrictions If Clock Overlap Requirement Is Met			

Features (Cont'd):

- Low power dissipation
0.3 mW/bit at 1 MHz and 10 V
0.04 mW/bit at 0.5 MHz and 5V
(alternating 1-0 data pattern)
- Data output TTL-DTL compatible
- Recirculating capability
- Delayed two-phase clock outputs available for cascading registers
- Asynchronous ripple-type presettable to all 1's or 0's
- Ultra-low-power-dissipation standby operation
- Quiescent current specified to 15 V
- Maximum input leakage current of 1 μA at 15 V (full package-temperature range)
- 1-V noise margin (full package-temperature range)

Applications:

- Serial shift registers
- Time-delay circuits
- CRT refresh memory
- Long serial memory

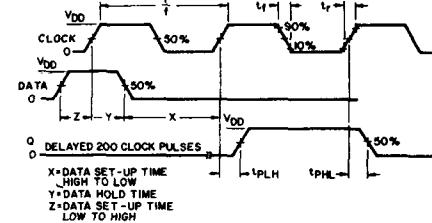


Fig. 3 — Timing diagram—single-phase clock.

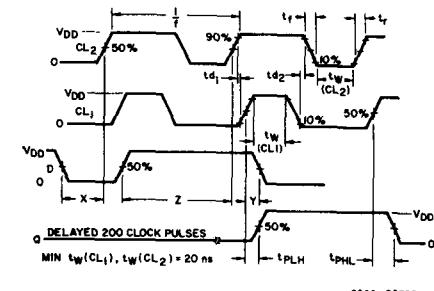


Fig. 4 — Timing diagram—two-phase clock.

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STATIC ELECTRICAL CHARACTERISTICS

CHARACTERISTICS	CONDITIONS			LIMITS AT INDICATED TEMPERATURES (°C)			UNITS	
	V _O (V)	V _{IN} (V)	V _{DD} (V)	-55	+25	+125		
	TYP.	LIMIT						
Quiescent Device Current, I _L Max. CM=High, CL ₁ =High, CL ₂ =Low	—	—	5	12	0.5	12	720	μA
	—	—	10	25	1	25	1500	
	—	—	15	50	1	50	2000	
Output Voltage: Low Level, V _{OL}	—	5	5	0 Typ.; 0.05 Max			V	
	—	10	10	0 Typ.; 0.05 Max				
High Level V _{OH}	—	0	5	4.95 Min.; 5 Typ.				
	—	0	10	9.95 Min.; 10 Typ.				
Noise Immunity: Inputs Low, V _{NL}	4.2	—	5	1.5 Min.; 2.25 Typ.			V	
	9	—	10	3 Min.; 4.5 Typ.				
Inputs High V _{NH}	0.8	—	5	1.5 Min.; 2.25 Typ.				
	1	—	10	3 Min.; 4.5 Typ.				
Noise Margin: Inputs Low, V _{NML}	4.5	—	5	1 Min.			V	
	9	—	10	1 Min.				
Inputs High, V _{NMH}	0.5	—	5	1 Min.				
	1	—	10	1 Min.				
Output Drive Current: N-Channel (Sink), I _{DN} Min.							mA	
	Q	0.4	—	4.5	1.6	2.6	1.3	
	Output	0.5	—	10	5	8*	4	
	CL1D	0.5	—	5	0.87	1.4	0.7	
	CL2D	0.5	—	10	2.2	3.6	1.8	
P-Channel (Source): I _{DP} Min.							mA	
	Q	4.5	—	5	-0.31	-0.5	-0.25	
	Output	2.5	—	5	-0.93	-1.5	-0.75	
	CL1D	4.5	—	10	-0.87	-1.4	-0.7	
	CL2D	9.5	—	5	-0.43	-0.7	-0.35	
Input Leakage Current, I _{IL} , I _{IH}	Any Input						μA	
	—	—	15	±10 ⁻⁵ Typ., ±1 Max.				

* Maximum power dissipation rating ≤ 200 mW.

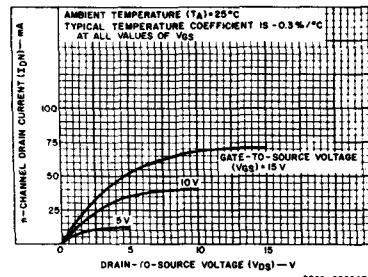


Fig. 5—Typical n-channel drain characteristics for Q output.

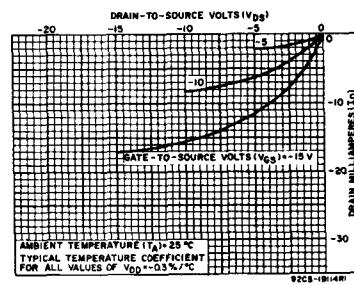


Fig. 6—Typical p-channel drain characteristics for Q output.

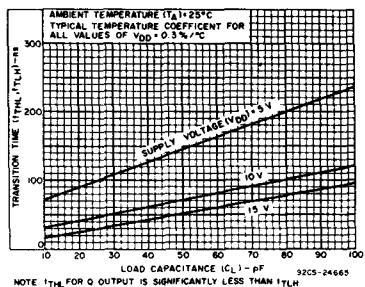


Fig. 7—Typical transition time vs. C_L for data outputs.

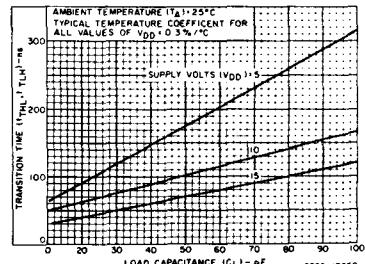


Fig. 8—Typical transition time vs. C_L for delayed clock output.

CD4062A Types

DYNAMIC CHARACTERISTICS AT $T_A = 25^\circ\text{C}$, $V_{SS} = 0\text{ V}$, $C_L = 50\text{ pF}$, Input $t_r, t_f = 20\text{ ns}$, except t_rCL and t_fCL

Single-Phase-Clock Operation; Clock Mode (CM) = Low; $3\text{ V} \leq V_{DD} \leq 10\text{ V}$ (See Figure 3)

CHARACTERISTIC	TEST CONDITIONS	LIMITS			UNITS
		V_{DD} V	MIN.	TYP.	
Maximum Clock Input Frequency, f_{CL} (50% Duty Cycle)	$t_r, t_f = 20\text{ ns}$	5	0.5	1	MHz
		10	1	2	
Minimum Clock Input Frequency, f_{CL} (50% Duty Cycle)		5	150	10	Hz
		10	150	10	
Clock Rise and Fall Times** t_rCL, t_fCL		5	—	—	10
		10	—	—	1 μs
Average Input Capacitance, C_I	All Inputs Except CL_1 and CL_2	—	5	—	pF
Propagation Delays:		5	—	1000	2000
		10	—	400	800
CL to Q		5	—	750	1500
		10	—	300	600
CL to CL_{1D} (Positive Going)	(50% Points)	5	—	500	1000
		10	—	200	400
CL to CL_{2D} (Positive Going)	(50% Points)	5	—	450	900
		10	—	175	350
CL to CL_{1D} (Negative Going)	(50% Points)	5	—	750	1500
		10	—	300	600
CL to CL_{2D} (Negative Going)	(50% Points)	5	—	450	900
		10	—	175	350
Transition Time: t_{TLH}, t_{THL}		5	—	100	200
		10	—	50	100
Q Output		5	—	200	400
		10	—	100	200
CL to CL_{1D} , CL_{2D}		5	—	100	200
		10	—	50	100
Data Set-Up Time		5	—	—	0
t_S		10	—	—	0
Data Hold Time		5	—	—	150
		10	—	—	150
t_H		5	—	—	ns
D		10	—	—	ns

** If more than one unit is cascaded in single-phase parallel clocked application, t_rCL should be made less than or equal to the sum of the propagation delay at 15 pF , and the transition time of the output driving stage. (See Figs. 5 and 7 for cascading options.)

▲ Use of delayed clock permits high-speed logic to precede CD4062A register (see cascade register operation).

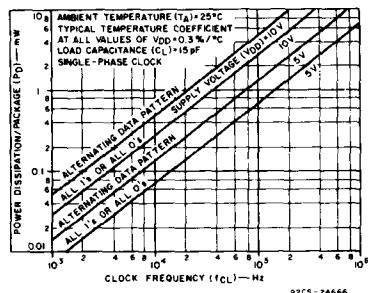
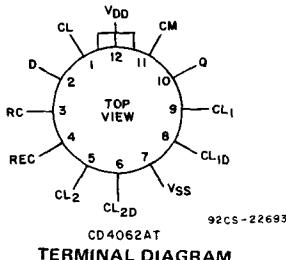


Fig. 9—Typical power dissipation vs. frequency.

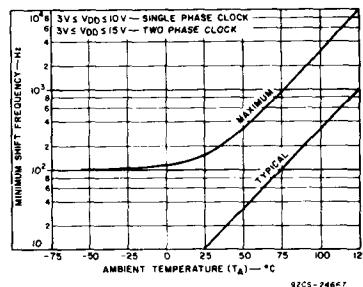


Fig. 10—Minimum shift frequency vs. ambient temperature.

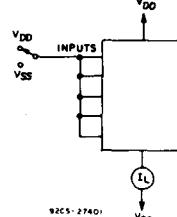


Fig. 11—Quiescent-device-current test circuit.

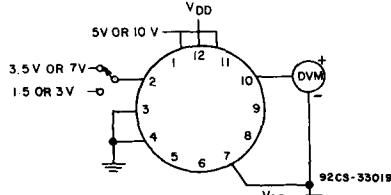


Fig. 12—Noise-immunity test circuit.

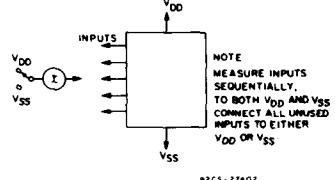


Fig. 13—Input-leakage-current test circuit.